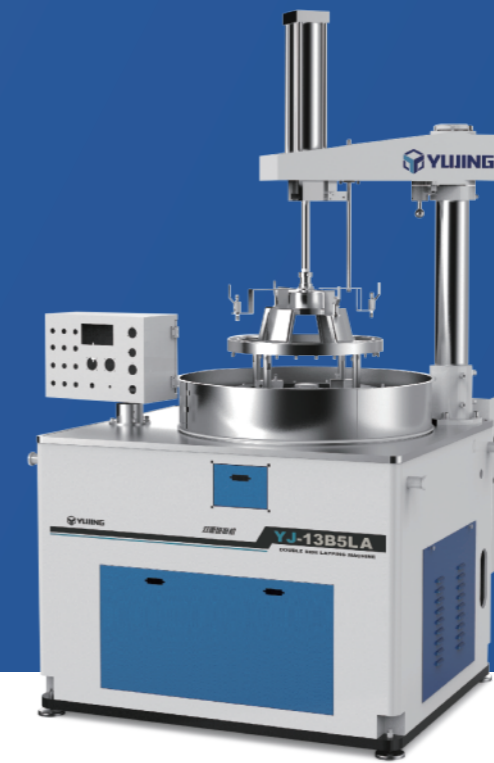


## DOUBLE SIDED LAPPING/POLISHING MACHINE

# 双面研磨/抛光机YJ-13B5L/PA

本机器主要用于半导体材料、金属、非金属工件（如阀板、刚性密封垫、活塞环、宝石制品、玻璃制品等）的平面研磨。也适用于超薄、脆性材料制成工件（如石英晶体）的研磨。

This machine is suitable for lapping and polishing of semi-conductor material, metal, and non-metal parts such as valve plate, rigid seal pad, piston ring, sapphire, and glass, as well as ultra-thin and fragile parts, such as quartz crystal.



手机盖板



玻璃屏

### 设备特点

- 机器采用双电机驱动，游星轮在上下盘之间做行星运动，工件上下表面同时均匀研磨/抛光；
- 机器采用内齿圈升降，内齿圈升降采用点动控制方式操作，使操作者能自由控制齿圈升降高度；
- 电机均使用变频器控制，能在有效设置范围内以任意速度工作，停止、加减速过程平稳，无抖动、无冲击；
- 上盘装置增加机械的安全装置，在摆片、维修等状态下不会因突然故障而下降，增加了安全性；
- 太阳轮可以任意调速，根据客户的要求可以方便的调整游星轮转速，实现盘面的修磨。

### MAIN TECHNICAL FEATURES

- Two motors. Carriers rotate between upper and lower plates. Both sides of work pieces can be evenly lapped.
- Ring gear position is adjustable by jog operation.
- Variable frequency speed governor realizes soft start, and soft stop. Machine can work under any speed which is within setting range. Speed changing is stable, and with no impact.
- Mechanical safety device prevents upper plate from falling down.
- Carriers can rotate clockwise and counter-clockwise by adjusting sun gear speed. It will realize plate conditioning.

### 主要技术参数 MAIN TECHNICAL SPECIFICATIONS

项目/Items	规格/Specs
上、下盘尺寸(Upper、lower plate size)	φ849×φ274×30 mm
工件厚度(Thickness of workpiece)	25 mm
工件直径(Dimensions of workpiece)	φ270 mm
下盘转速(Dimensions of workpiece)	0 ~ 60 rpm
游星轮数量(Number of Planet gears)	5
内齿圈抬升行程 (Lifting stroke of inner gear ring)	0 ~ 25 mm
安全装置气缸行程(Cylinder stroke of safety device)	0 ~ 30mm)
主电机(Main motor)	3相(phase) 7.5 kw 1450 r/min
副电机(Vice motor)	3相(phase) 0.75 kw 1450 r/min
砂泵电机(Slurry pump motor)	250 W
气源压力(Air pressure)	0.5-0.6 Mpa
工作压力(Working pressure)	0.45-0.6 Mpa
外形尺寸(Size L×W×H)	1545×1500×2810 mm
机器重量(Weight)	~ 3200 Kg